

150 V, 3.9 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

30 April 2024 Product data sheet

1. General description

The GANE3R9-150QBA is a a general purpose 150 V, 3.9 m Ω Gallium Nitride (GaN) FET in a Very-Thin-Profile Quad Flat No-Lead Package (VQFN) package. It is a normally-off e-mode device offering superior performance and very low on-state resistance.

2. Features and benefits

- · Enhancement mode normally-off power switch
- · Ultra high frequency switching capability
- · No body diode
- · Low gate charge, low output charge
- Qualified for standard applications
- RoHS, Pb-free, REACH-compliant
- · High efficiency and high power density
- Very-Thin-Profile Quad Flat No-Lead Package (VQFN) 4.0 mm x 6.0 mm

3. Applications

- · High power density and high efficiency power conversion
- AC-to-DC converters, (secondary stage)
- High frequency DC-to-DC converters in 48 V systems
- Fast battery charging, mobile phone, laptop, tablet and USB type-C chargers
- Datacom and telecom (AC-to-DC and DC-to-DC) converters
- Motor drives
- LiDAR (non-automotive)
- Class D audio amplifiers

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DS}	drain-source voltage	-40 °C ≤ T _j ≤ 150 °C	-	-	150	V
I _D	drain current	V _{GS} = 5 V; T _{mb} = 25 °C	-	-	100	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	-	65	W
Tj	junction temperature		-40	-	150	°C
Static chara	cteristics					
R _{DSon}	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 30 \text{ A}; T_j = 25 \text{ °C}; Fig. 8; Fig. 9$	-	3.2	3.9	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 30 \text{ A}; T_j = 150 \text{ °C}; Fig. 8; Fig. 10$	-	7	-	mΩ
R_G	gate resistance	f = 5 MHz	-	1.9	-	Ω



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Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Dynamic chara	acteristics						
Q_{GD}	gate-drain charge	I _D = 30 A; V _{DS} = 75 V; V _{GS} = 5 V;		-	3.5	-	nC
Q _{G(tot)}	total gate charge	T _j = 25 °C; <u>Fig. 11</u> ; <u>Fig. 12</u>		-	20	-	nC
Q _{oss}	output charge	V _{GS} = 0 V; V _{DS} = 75 V; <u>Fig. 15</u>	[1]	-	130	-	nC

^[1] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and $Q_D = 0$. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1,2,25	G	gate	7 [1 1 25	
3-7,9,11, 21,23	S	source		D _.
8,10,12- 20,22,24		drain	12 20 13 19 Transparent top view	G - S
			VQFN7 (SOT8091-1)	

6. Ordering information

Table 3. Ordering information

Table of Oracining Information							
Type number	Package	ge					
	Name	Description	Version				
GANE3R9-150QBA	VQFN7	very thin quad flatpack; no leads	SOT8091-1				

7. Marking

Table 4. Marking codes

-	W. 11
Type number	Marking code
GANE3R9-150QBA	3R9EQBA

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	-40 °C ≤ T _j ≤ 150 °C	-	150	V
V_{GS}	gate-source voltage		-4	6	V
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	65	W
I _D	drain current	V _{GS} = 5 V; T _{mb} = 25 °C	-	100	Α
I _{DM}	peak drain current	pulsed; t _p = 100 μs; T _{mb} = 25 °C; <u>Fig. 2</u>	-	260	Α
T _{stg}	storage temperature		-40	150	°C
Tj	junction temperature		-40	150	°C
$T_{sld(M)}$	peak soldering temperature		-	260	°C

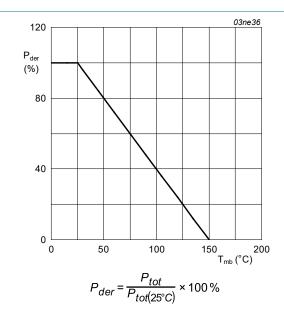
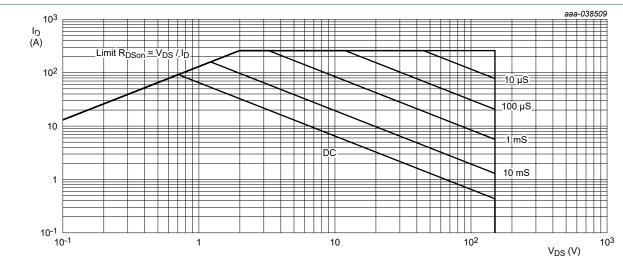


Fig. 1. Normalized total power dissipation as a function of mounting base temperature



T_{mb} = 25 °C; I_{DM} is a single pulse

Fig. 2. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-c)}	thermal resistance from junction to case			-	13.96	-	K/W
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	Fig. 3		-	1.92	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1]	-	57.56	-	K/W

[1] R_{th(j-a)} is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.

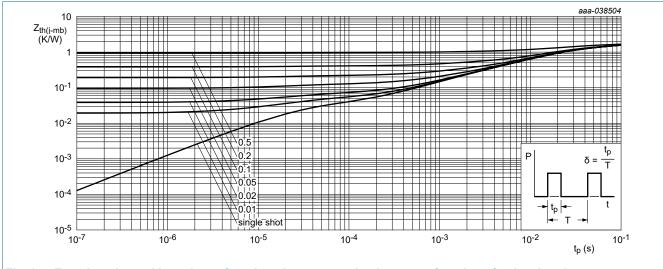


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static chara	acteristics						
V _{GS(th)}	gate-source threshold	$I_D = 12 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}; Fig. 7$		8.0	1.1	2.1	V
voltage		I_D = 12 mA; V_{DS} = V_{GS} ; T_j = 150 °C; Fig. 7		-	1	-	V
I _{DSS}	drain leakage current	V _{DS} = 150 V; V _{GS} = 0 V; T _j = 25 °C		-	2	150	μΑ
I _{GSS}	gate leakage current	V _{GS} = 5 V; T _j = 25 °C		-	2	100	μΑ
		V _{GS} = 6 V; T _j = 25 °C		-	6	1000	μΑ
		V _{GS} = -4 V; T _j = 25 °C		-	0.1	100	μΑ
R_{DSon}	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 30 \text{ A}; T_j = 25 \text{ °C}; Fig. 8; Fig. 9}$		-	3.2	3.9	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 30 \text{ A}; T_j = 150 °C; Fig. 8; Fig. 10$		-	7	-	mΩ
R_G	gate resistance	f = 5 MHz		-	1.9	-	Ω
Dynamic ch	naracteristics						'
Q _{G(tot)}	total gate charge	I _D = 30 A; V _{DS} = 75 V; V _{GS} = 5 V; T _j = 25 °C; <u>Fig. 11</u> ; <u>Fig. 12</u>		-	20	-	nC
Q _{GS}	gate-source charge			-	5	-	nC
Q _{GD}	gate-drain charge	1		-	3.5	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	I _D = 30 A; V _{DS} = 75 V		-	2	-	V
C _{iss}	input capacitance	V _{DS} = 75 V; V _{GS} = 0 V; f = 100 kHz;		-	2200	-	pF
C _{oss}	output capacitance	T _j = 25 °C; <u>Fig. 13</u>		-	900	-	pF
C _{rss}	reverse transfer capacitance			-	10.5	-	pF
C _{o(er)}	effective output capacitance, energy related	$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C};$ Fig. 14		-	1300	-	pF
C _{o(tr)}	effective output capacitance, time related	$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$		-	1700	-	pF
Q _{oss}	output charge	V _{GS} = 0 V; V _{DS} = 75 V; <u>Fig. 15</u>	[1]	-	130	-	nC
Source-dra	in characteristics						
V_{SD}	source-drain voltage	I _S = 0.5 A; V _{GS} = 0 V; T _j = 25 °C; Fig. 16; Fig. 17; Fig. 18; Fig. 19		-	1.5	-	V

^[1] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and $Q_D = 0$. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)

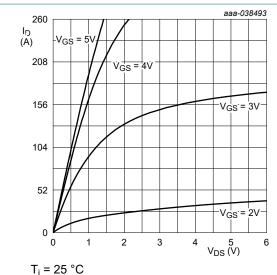


Fig. 4. Output characteristics: drain current as a function of drain-source voltage; typical values

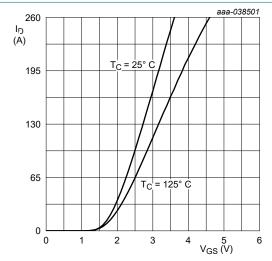


Fig. 6. Transfer characteristics; drain current as a function of gate-source voltage; typical values

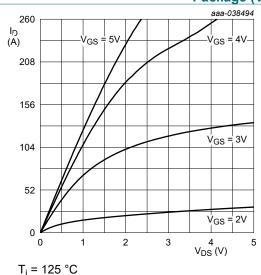
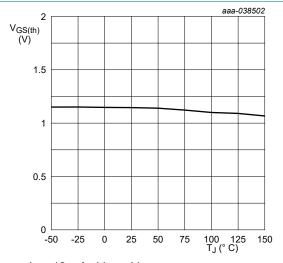


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values



 I_D = 12 mA ; V_{DS} = V_{GS}

Fig. 7. Gate-source threshold voltage as a function of junction temperature

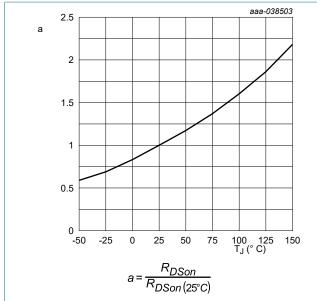


Fig. 8. Normalized drain-source on-state resistance factor as a function of junction temperature

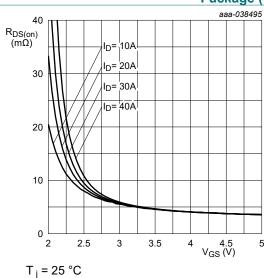


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

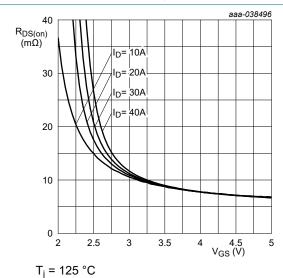


Fig. 10. Drain-source on-state resistance as a function of gate-source voltage; typical values

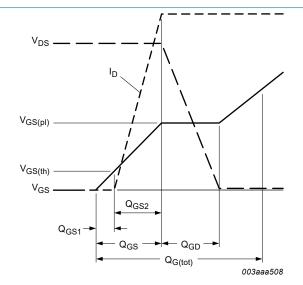


Fig. 11. Gate charge waveform definitions

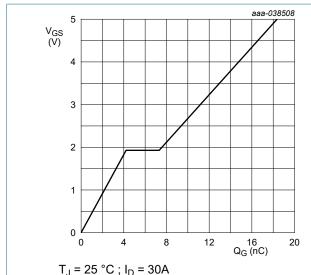


Fig. 12. Gate-source voltage as a function of gate charge; typical values

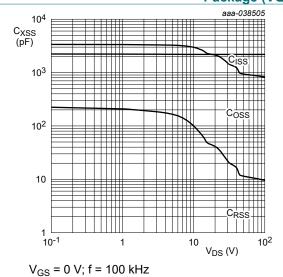


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical

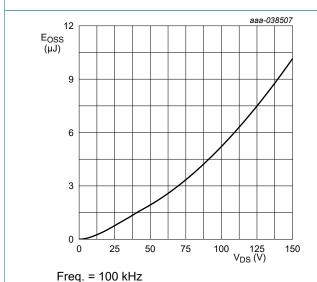


Fig. 14. COSS stored energy as a function of drainsource voltage; typical values

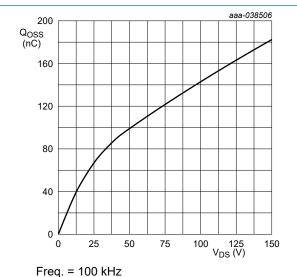


Fig. 15. Output charge as a function of drain-source voltage; typical values

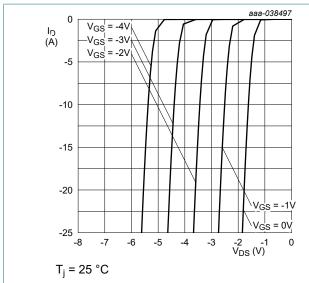


Fig. 16. Source current as a function of source-drain voltage; typical values

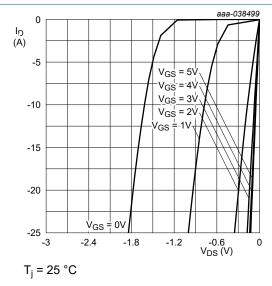


Fig. 18. Source current as a function of source-drain voltage; typical values

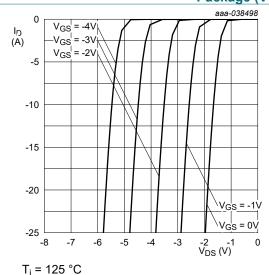


Fig. 17. Source current as a function of source-drain voltage; typical values

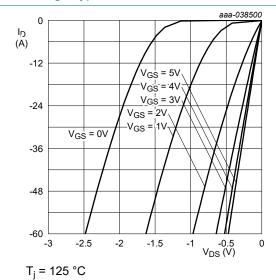
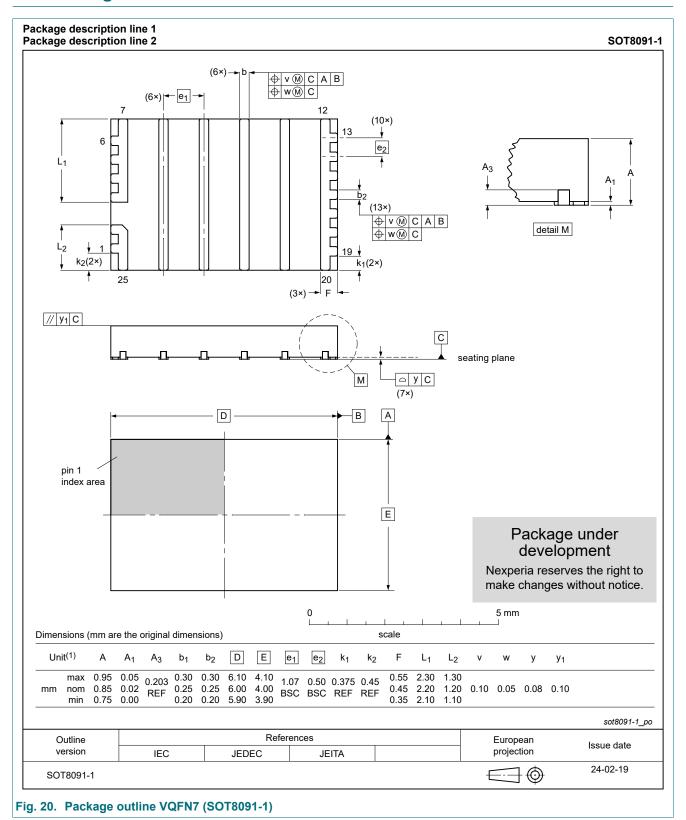


Fig. 19. Source current as a function of source-drain voltage; typical values

11. Package outline



12. Soldering

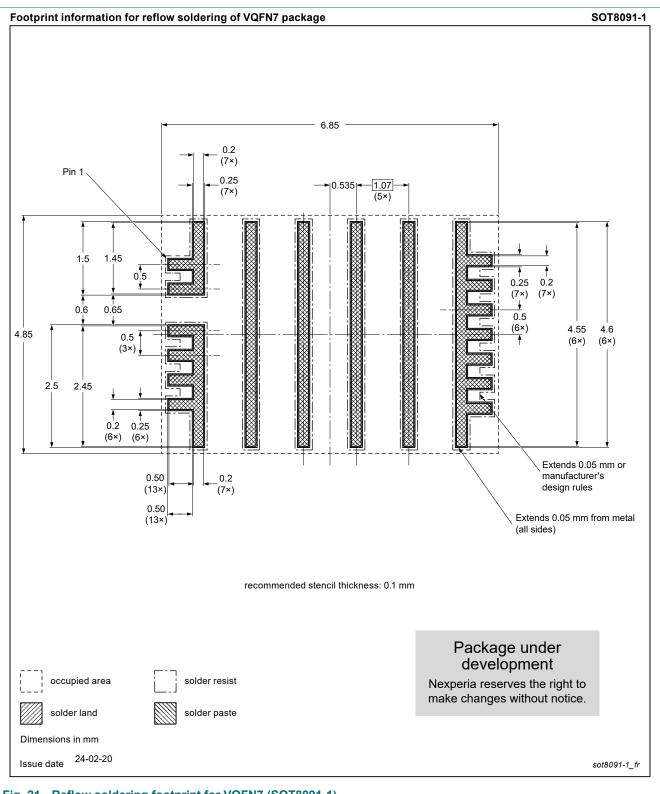


Fig. 21. Reflow soldering footprint for VQFN7 (SOT8091-1)

13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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